imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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XP04111

Silicon PNP epitaxial planar type

For digital circuits

Features

- Two elements incorporated into one package (Transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

Basic Part Number

• UNR2111 × 2

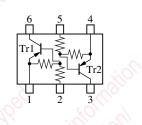
Absolute Maximum Ratings $T_a = 25^{\circ}C$

Symbol	Rating	Unit	
V _{CBO}	-50	V	
V _{CEO}	-50	V	
I _C	-100	mA	
P _T	150	mW	
Tj	150	°C	
T _{stg}	-55 to +150	°C	
	V_{CBO} V_{CEO} I_C P_T T_j	$\begin{array}{c c} V_{CBO} & -50 \\ \hline V_{CEO} & -50 \\ \hline I_C & -100 \\ \hline P_T & 150 \\ \hline T_j & 150 \\ \hline \end{array}$	

Package

- Code
 SMini6-G1
- Pin Name
 - 1: Emitter (Tr1) 4: Emitter (Tr2)
 - 5: Base (Tr2)
 - 2: Base (Tr1) 3: Collector (Tr2)
 - 6: Collector (Tr1)
- Marking Symbol: 9U

Internal Connection



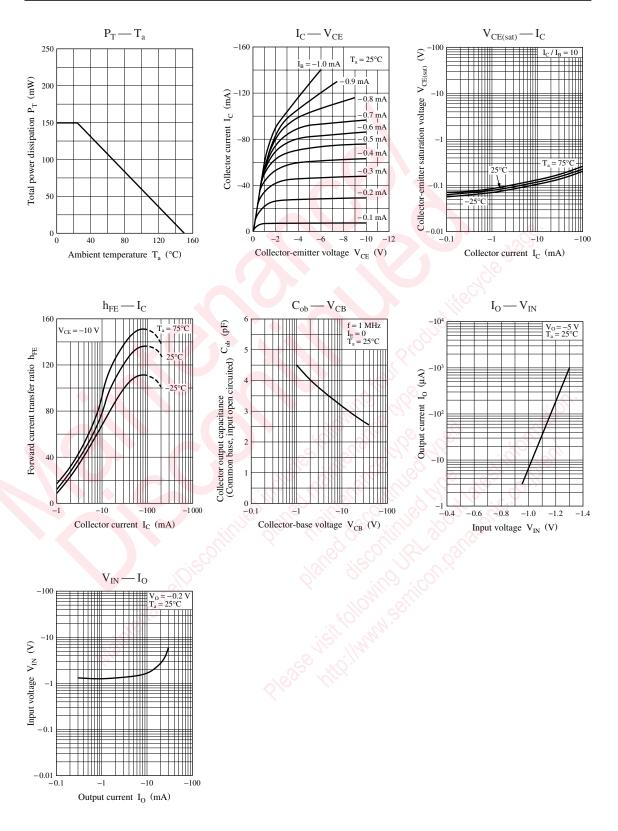
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \ \mu \text{A}, I_{\rm E} = 0$	-50			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-50			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = -50 \text{ V}, I_E = 0$			- 0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -50 \text{ V}, I_B = 0$			- 0.5	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = -6 V, I_C = 0$			- 0.5	mA
Forward current transfer ratio	h _{FE}	$V_{CE} = -10 \text{ V}, I_C = -5 \text{ mA}$	35			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -10 \text{ mA}, I_{\rm B} = -0.3 \text{ mA}$			- 0.25	V
Output voltage high-level	V _{OH}	$V_{CC} = -5 \text{ V}, \text{V}_{B} = -0.5 \text{V}, \text{R}_{L} = 1 \text{k}\Omega$	-4.9			V
Output voltage low-level	V _{OL}	$V_{CC} = -5 \text{ V}, \text{ V}_{B} = -2.5 \text{ V}, \text{ R}_{L} = 1 \text{ k}\Omega$			- 0.2	V
Input resistance	R ₁		-30%	10	+30%	kΩ
Resistance ratio	R ₁ / R ₂		0.8	1.0	1.2	
Transition frequency	f _T	$V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

XP04111

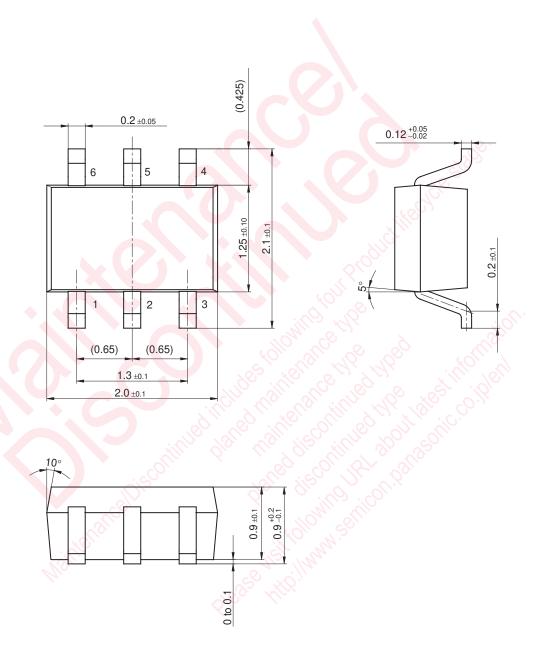




Panasonic

SMini6-G1

Unit: mm



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